ABBOCIATION CONNECTING ALECTRONICS INDUSTRIES® INTERNATIONAL AND INTERNATIONAL CONNECTING	mposition Dec 05. IPC, Bannockt d Pan-American co	c laration ourn, Illinois. A pyright conve	All rights reserved u ntions.	nder both	This docume level parts, th	ent is a declaration entities of the declaration entities	on of the substancompasses all	nces within lower level r	the manufactur naterials for w	rer listed iten hich the man	n. Note: if ufacturer	the item is an as has engineering	sembly with low responsibility.
				Form Type ⁵ Distribute	e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater				ials and Mfg Information				
upplier Information													
ompany name*	Company unique ID			ī	Unique ID Authority				Response Date*				
onsemi										2025-05-11			
Contact Name Title			Title - Contact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards P.			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title			Fitle - Representative			Phone - Representative*				Email - Representative*			
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		We	ight*	UOM	Unit Type
	NOIP1S	NOIP1SF0480A-STI PY		PYTHON480 1/3.6", RGB_ CRA23.59		2025-05-11		TWU	TWU		3603	mg	Each
Ianufacturing Proccess Infor	mation										_		
Terminal Plating / Grid Arra	Terminal Plating / Grid Array Material Term		erminal Base Alloy J-STD-020 MSL		Rating	Peak Process Body Temperature		erature Max	Time at Peak	Temperature	Numb	er of Reflow Cyc	les
SnAgCu		CU Alloy 4		1		245 C		30	30 sec		3		
omments													
or more information regarding mate	erial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all						
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.6894	mg	Supplier	Silicon (Si)	7440-21-3		6.6894	mg
Glass Attach Epoxy	0.0053	mg		Miscellaneous	trade secret		0.0007	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0046	mg
Glass Lid /Cap	29.3747	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.9375	mg
			Supplier	Magnesium Monoxide (MgO)	1309-48-4		1.4687	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		1.4687	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.9375	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		1.4687	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		19.0936	mg
Metal Shielding	0.0483	mg	Supplier	Copper (Cu)	7440-50-8		0.0002	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0481	mg
RDL	0.053	mg	В	Nickel (Ni)	7440-02-0		0.0328	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.0001	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0198	mg
Solder Ball	2.1563	mg	Supplier	Silver (Ag)	7440-22-4		0.0647	mg
			Supplier	Tin (Sn)	7440-31-5		2.0808	mg
			Supplier	Copper (Cu)	7440-50-8		0.0108	mg
Substrate and Solder Mask	0.0333	mg	Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.0033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0017	mg
			Supplier	2-Propenoic acid	1245638-61-2		0.0033	mg
			Supplier	3-Methoxy-1-butanol	2517-43-3		0.0083	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0083	mg
			Supplier	1-Methoxy-2-propyl acetate (MPA)	108-65-6		0.0083	mg